

DECLARATION FOR PATENT APPLICATION

As a below named inventor(s), I (we) hereby declare that:

My (our) residence(s), post office address(es) and citizenship(s) is (are) the same as stated below next to my (our) name(s).

I (we) believe I am (we are) an original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled: **METHOD FOR ANALYZING IMPURITIES IN A SILICON SUBSTRATE AND APPARATUS FOR DECOMPOSING A SILICON SUBSTRATE THROUGH VAPOR-PHASE REACTION**

the specification of which is attached hereto unless the following box is checked:

☐ was filed on _____ as United States Application Number _____ or PCT International Application Number _____ and was amended on _____ (if applicable).

I (we) hereby state that I (we) have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above.

I (we) acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations, §1.56.

I (we) hereby claim foreign priority benefits under Title 35, United States Code, §119(a)-(d) of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

Prior Foreign Application(s):			Priority Claimed:	
(Number)	(Country)	(Day/Month/Year)	YES	NO

I (we) hereby claim the benefit under Title 35, United States Code, §119(e) of any United States provisional application(s) listed below:

(Application Number)

(Filing Date)

I (we) hereby claim the benefit under Title 35, United States Code, § 120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, § 112, I (we) acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulation, §1.56 which became available between the filing date of the prior application and the national or PCT international filing date of this application.

(Application Serial No.)	(Filing date)	(STATUS-patented, pending, abandoned)

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I (we) hereby appoint the following attorney(s) and/or agent(s) to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith and to act in accordance with the instructions from Suda Patent Office:

Lloyd McAulay,
Jules E. Goldberg,
Eugene LeDonne,
Arthur Dresner,

Reg. No. 20,423;
Reg. No. 24,408;
Reg. No. 35,930;
Reg. No. 36,612;

J. Harold Nissen,
Gerald H. Kiel,
Stephen M. Chin,
Samir R. Patel,

Reg. No. 17,283;
Reg. No. 25,116;
Reg. No. 39,938;
Reg. No. 44,998

all of Reed Smith LLP, 375 Park Avenue, New York, New York 10152-1799

Address all telephone calls to: Jules E. Goldberg, Esq. at Telephone No. (212) 521-5400

Address all correspondence to: Jules E. Goldberg, Esq.
Reed Smith LLP
375 Park Avenue, New York, NY 10152-1799 U.S.A.

I (we) hereby declare that all statements made herein of my (our) own knowledge are true, and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Full name of sole or 1st inventor (given name, family name):		Mohammad B. Shabani	
Residence:	Tokyo, Japan	Citizenship:	Iran
Post Office Address:	c/o MITSUBISHI MATERIALS SILICON CORPORATION, 5-1, Ohtemachi 1-chome, Chiyoda-ku, Tokyo 100-0004 Japan		

Inventor's signature: MOHAMMA B. SHABANI SHABANI Date: 2004, 1, 18

Full name of 2nd inventor (given name, family name):		Shigeru Okuuchi	
Residence:	Tokyo, Japan	Citizenship:	Japan
Post Office Address:	c/o MITSUBISHI MATERIALS SILICON CORPORATION, 5-1, Ohtemachi 1-chome, Chiyoda-ku, Tokyo 100-0004 Japan		

Inventor's signature:  Date: 2001. 1. 19

Full name of 3rd inventor (given name, family name):			
Residence:		Citizenship:	
Post Office Address:			

Inventor's signature: _____ Date: _____